

# Product / Process Change Notification



N° 2018-171-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

## Introduction of an additional wafer production location with 8" wafer diameter for IGBT3 600/650V technology and diode EC3 600/650V technology

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **22<sup>nd</sup> January 2019**.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates:  
"Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG  
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Chairman of the Supervisory Board: Dr. Eckart Süner  
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck  
Registered Office: Neubiberg Commercial Register  
Amtsgericht München HRB 126492

# Product / Process Change Notification



N° 2018-171-A

► **Products affected:**

Please refer to attached affected product list  
"pcn\_2018-171-A\_[customer-no].pdf"

► **Detailed Change Information:**

**Subject:** Introduction of an additional wafer production location with 8" wafer diameter for IGBT3 600/650V technology and diode EC3 600/650V technology

**Reason:** Capacity extension and increasing security of supply IGBT3 and diode EC3 600/650V

**Description:**

<u>Old</u>	<u>New</u>
■ <b>IGBT</b> <u>8" inch:</u> - Front end Villach/ Austria	■ <b>IGBT</b> <u>8" inch:</u> - Front end Villach/ Austria - Front end Kulim/ Malaysia  ➔ Target production location front end Kulim/ Malaysia
■ <b>Diode</b> <u>8" inch:</u> - Front end Villach/ Austria	■ <b>Diode</b> <u>8" inch:</u> - Front end Villach/ Austria - Front end Kulim/ Malaysia  ➔ Target production location front end Kulim/ Malaysia

► **Product Identification:**

Individual production lot number

► **Impact of Change:**

No change of datasheet. Quality and reliability verified by qualification.  
There is no change in form, fit and function of the module.

► **Attachments:**

Affected product list "pcn\_2018-171-A\_[customer-no].pdf"

► **Time Schedule:**

- Final qualification report: available
- First samples available: on request
- Intended start of delivery: 15-December-2018 depending on customer approval

If you have any questions, please do not hesitate to contact your local Sales office.

### PCN 2018-171-A

Introduction of an additional wafer production location with 8" wafer diameter for IGBT3  
600/650V technology and diode EC3 600/650V technology



Affected products sold to FUTURE ELECTRONICS INC. (4000624)

Sales name	SP number	OPN	Package	Customer part number
F3L150R07W2E3_B11	SP000638568	F3L150R07W2E3B11BOMA1	AG-EASY2B-2-1	F3L150R07W2E3B11BOMA1
F3L200R07PE4	SP000711882	F3L200R07PE4BOSA1	AG-ECONO4-1-1	F3L200R07PE4BOSA1
F3L400R12PT4_B26	SP000929974	F3L400R12PT4B26BOSA1	AG-ECONO4-1-1	F3L400R12PT4B26BOSA1
FS100R06KE3	SP000091926	FS100R06KE3BOSA1	AG-ECONO3-4-1	FS100R06KE3BOSA1
FS150R06KE3	SP000091927	FS150R06KE3BOSA1	AG-ECONO3-4-1	FS150R06KE3BOSA1
FS200R06KE3	SP000091928	FS200R06KE3BOSA1	AG-ECONO3-4-1	FS200R06KE3BOSA1
FS20R06VE3	SP000100335	FS20R06VE3BOMA1	AG-EASY750-1-1	FS20R06VE3BOMA1